

## CLAIMS

1. A composition for cleaning a positive or negative photoresist which comprises (a) from 0.1 to 20 wt.% of an alkyl oxide polymer with a molecular weight of from 50 to 2000; and (b) from 80 to 99.9 wt.% of an organic solvent containing from 1 to 20 parts by weight of dipropylene glycol alkyl ether (DPGAE), from 10 to 50 parts by weight of N-methyl pyrrolidone(NMP) and from 50 to 90 parts by weight of methyl isobutyl ketone (MIBK).
2. The composition for cleaning a positive or negative photosensitive material of claim 1, wherein the alkyl oxide polymer is ethylene oxide polymer.
3. The composition for cleaning a positive or negative photosensitive material of claim 1, wherein the alkyl oxide polymer is propylene oxide polymer.
4. The composition for cleaning a positive or negative photosensitive material of any one of claims 1 to 3, wherein the dipropylene glycol alkylether is dipropylene glycol methyl ether.
5. A composition for cleaning a positive or negative photoresist which comprises (a) from 0.1 to 20 wt.% of an alkyl oxide polymer with a molecular weight of from 50 to 2000; and (b) from 80 to 99.9 wt.% of an organic solvent containing from 10 to 90 parts by weight of dimethyl formamide (DMF) or dimethylacetamide (DMAc) and from 10 to 50 parts by weight of n-butyl acetate.

6. The composition for cleaning a positive or negative photosensitive material of claim 5, wherein the alkyl oxide polymer is ethylene oxide polymer.

7. The composition for cleaning a positive or negative photosensitive material of claim 5, wherein the alkyl oxide polymer is propylene oxide polymer.